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### Contents

#### HYBRID INTEGRATED OPTICAL LINK MODULES

- 11692 04 Short reach, high temperature operation and high reliability silicon photonic micro-transceivers for embedded and co-packaged system integration (Invited Paper) [11692-1]
- 11692 05 **Co-packaged optics for HPC and data center networks (Invited Paper)** [11692-2]

#### **OPTICAL INTERCONNECT DEVICES**

- 11692 06 Monolithically integrable optical single sideband transmitter for low-cost, high-density optical interconnects (Invited Paper) [11692-3]
- 11692 07 Silicon photonic switches (Invited Paper) [11692-4]
- 11692 OC The role of VCSELs in 3D sensing and LiDAR [11692-9]
- 11692 0D NRZ, DB, and DMT performance for short-reach VCSEL-based optical interconnects [11692-10]

#### PICS FOR OPTICAL INTERCONNECTS

- 11692 0H From integrated photonic transceivers to all-optical logic (Invited Paper) [11692-14]
- 11692 01 Ultra-long grating emitters for optical phased array leveraging subwavelength structures (Invited Paper) [11692-15]

#### NOVEL OPTICAL WAVEGUIDE AND INTEGRATED INTERCONNECT TECHNOLOGIES

- 11692 OK
   Thermally stable single-mode glass waveguides with fiber connectors for co-packaged optics (Invited Paper) [11692-17]
- 11692 0M **3D nanoprinting of mode-field conversion tapers for low-loss optical interfacing of single-mode fibers and photonic integrated circuits (Invited Paper)** [11692-19]
- 11692 0N Interconnection challenges on integrated terahertz photonic systems (Invited Paper) [11692-20]

#### HYBRID DEVICE INTEGRATION APPROACHES FOR PIC

- 11692 OR Integrated high-speed quantum random number generators for mobile, IOT, and edge applications (Invited Paper) [11692-24]
- 11692 0T A particle swarm optimization approach for designing III-V/Si vertical couplers [11692-26]

#### **OPTICAL INTERCONNECT SYSTEMS**

- 11692 0WA silicon photonic evanescent-field sensor architecture using a fixed-wavelength laser<br/>(Invited Paper) [11692-29]
- 11692 0X An overview of key optical communications technologies under development at the NASA Glenn Research Center (Invited Paper) [11692-30]
- 11692 0Z Maximizing the impact of emerging photonic switches at the system level [11692-32]
- 11692 10 **Resilient architectures for free space optical wireless interconnection systems** [11692-33]

#### FIBER OPTICS AND MICRO-OPTIC ASSEMBLY

- 11692 13 **Probabilistic deep neural network based signal processing for Brillouin gain and phase** spectrums of vector BOTDA system [11692-36]
- 11692 14 Next generation multi-fiber ferrule using 165 micron pitch optical fiber [11692-37]
- 11692 18 Extremely low-loss and bendable tapered multi-core fiber with double core structure for compact assembly of silicon photonics multi-port devices [11692-41]